

The listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Canceled)

2. (Previously Presented) A display device comprising:

a glass substrate;

a lead formed over the glass substrate, said lead comprising a first layer comprising silver and a second layer comprising indium tin oxide formed on the first layer;

an IC chip provided over the glass substrate and electrically connected to the lead wherein a pad of the IC chip is electrically connected to the second layer of the lead.

3. (Previously Presented) The display device according to claim 2 wherein said first layer is formed by applying a conductive paste over the glass substrate and then baking said conductive paste.

4. (Previously Presented) A display device comprising:

a glass substrate;

a lead formed over the glass substrate, said lead comprising a first layer comprising silver and a second layer comprising indium tin oxide formed on the first layer;

an IC chip provided over the glass substrate with an adhesive therebetween and electrically connected to the lead wherein a pad of the IC chip is electrically connected to the second layer of the lead,

wherein said adhesive comprises a resin and metal particles.

5. (Previously Presented) The display device according to claim 4 wherein said adhesive comprises an epoxy resin.

6. (Previously Presented) The display device according to claim 4 wherein said metal particles are Ni particles.

7. (Previously Presented) A display device comprising:
a glass substrate;
a lead formed over the glass substrate, said lead comprising a first conductive layer and a second conductive layer comprising indium tin oxide formed on the first layer;
an IC chip provided over the glass substrate with an adhesive therebetween and electrically connected to the lead wherein a pad of the IC chip is electrically connected to the second conductive layer of the lead,
wherein said adhesive comprises a resin and metal particles.

8. (Previously Presented) The display device according to claim 7 wherein said adhesive comprises an epoxy resin.

9. (Previously Presented) The display device according to claim 7 wherein said metal particles are Ni particles.

10. (New) A display device comprising:
a glass substrate;
a lead formed over the glass substrate, said lead comprising a first conductive layer and a second layer comprising indium tin oxide formed on the first layer;

an IC chip provided over the glass substrate with an adhesive therebetween and electrically connected to the lead wherein a pad of the IC chip is electrically connected to the second layer of the lead,

wherein said adhesive comprises a resin and metal particles.

11. (New) The display device according to claim 10 wherein said adhesive comprises an epoxy resin.

12. (New) The display device according to claim 10 wherein said metal particles are Ni particles.